

Component Packaging Test Services

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Component Qualification Testing

Test Environments

- Temperature
- Temperature Cycling
- Temperature/Humidity
- Vibration
- Mechanical Shock
- Drop
- Bending
- Pull/Shear
- Combined Environment (Vibration + Temperature)

Test Methods

- JESD22 (A and B)
- AEC Q100
- IPC 97XX

Failure Analysis

- Decapsulation (gold and copper wire)
- Cross-Sectioning
- Optical and Electron Microscopy

Temperature and Temperature Cycling

- Sun Electronics
- Twenty Two (22) Test Chambers
 - Internal Convection Fans for Spatial Temperature Control
 - Gravity ovens for component thermal testing (theta Jc)
 - Up to 8 cubic feet
- Chamber Parameters
 - Up 40°C/min ramp rates
 - Max Temp of 315C
 - Min Temp of -150C



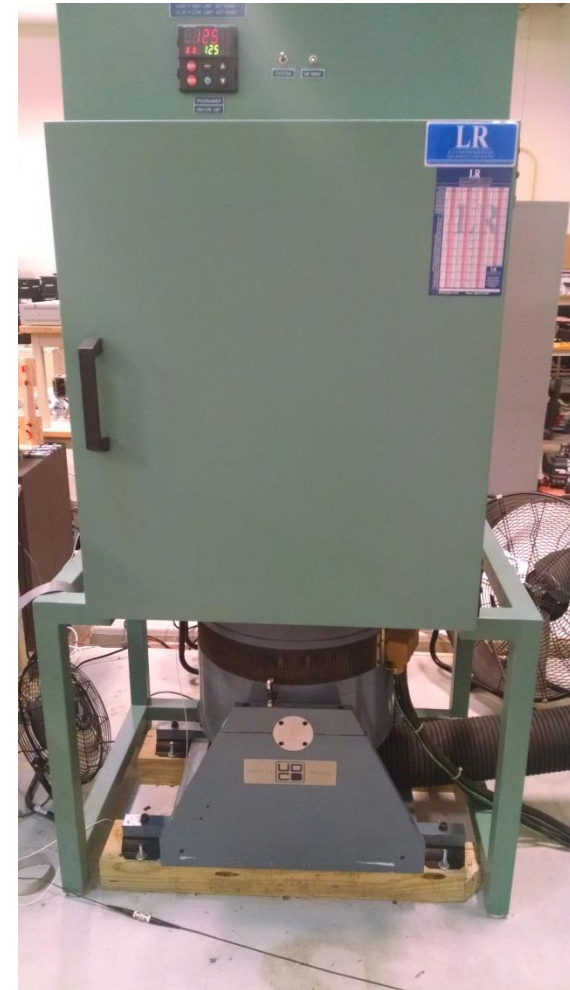
Temperature / Humidity

- ESPEC
- Three (3) Test chambers
 - Internal Convection Fans for Spatial Temperature Control
 - Up to 8 cubic feet
- Chamber Parameters
 - 0%RH to 98%RH
 - Up 5°C/min ramp rates
 - Max Temp of 100C
 - Min Temp of -40C



Vibration and Mechanical Shock

- Unholtz Dickie
- Capability
 - Sinusoidal and Random
 - 0 to 5000 Hz frequency
 - Up to 100G Shock
 - Up to 1,000 lbs Force
 - 10 lbs Armature Weight
 - 2 inch Displacement
 - Event Detector
- In combination with temperature or temperature cycling



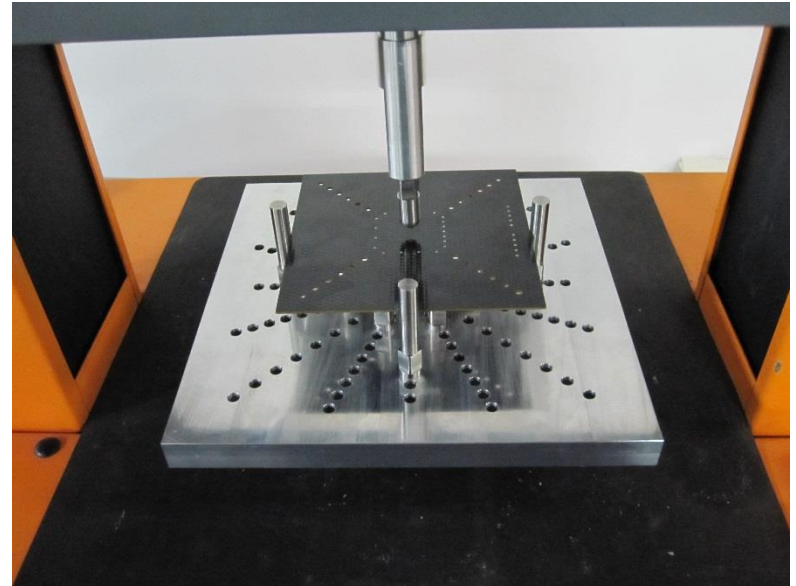
Drop Testing

- Lansmont
- Capability
 - Automated
 - Up to 125 drops per hour
 - Up to 3000 Gs of force
 - Half sine pulses with 0.2 to 1 ms pulse width
 - Event Detector



Bend Testing

- Instron, MTS, and Bose
- Multiple Mechanical Testers
- Capability
 - Cyclic and Monotonic
 - 3-Point, 4-Point, and 9-point
 - Up to 300 Hz
 - Up to 8500N
 - Single-Point Pressure to Measure Deflection Radially
 - Event Detector



Semiconductor Packaging Customers (Examples)

- Contact sales@dfrsolutions.com for a list of existing customers